

## EAST Search History

| Ref # | Hits    | Search Query                                                                                                                                                                                                         | DBs                                                               | Default Operator | Plurals | Time Stamp       |
|-------|---------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|------------------|---------|------------------|
| L1    | 2       | "6407334".pn.                                                                                                                                                                                                        | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:27 |
| L2    | 2       | "6410988".pn.                                                                                                                                                                                                        | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:34 |
| L3    | 1270597 | (semiconductor die chip dice ic element electronic flipchip (flip adj chip) (integrated adj circuit) microelectronic microprocessor) with (carrier substrate substrate ((wiring printed circuit mother) adj3 board)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:37 |
| L4    | 198653  | (cte thermal expansion coefficient (co adj efficient)) with (filling filiant fill\$4 epoxy resin)                                                                                                                    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:43 |
| L5    | 10220   | 3 same 4                                                                                                                                                                                                             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:40 |
| L6    | 1074810 | (spac\$3 stiffen\$4 stump post) with (surround\$4 encircl\$4 edg\$4 peripheral\$4 perimeter)                                                                                                                         | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:42 |
| L7    | 1119    | 5 and 6                                                                                                                                                                                                              | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 17:42 |
| L8    | 199366  | (cte thermal expansion coefficient (co adj efficient)) with (filling underfill fillet filiant fill\$4 epoxy resin)                                                                                                   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2007/07/01 20:10 |

## EAST Search History

|     |          |                                                                                                                             |                                                                   |    |    |                  |
|-----|----------|-----------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|----|----|------------------|
| L9  | 10846    | 3 same 8                                                                                                                    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:11 |
| L10 | 1240     | 9 and 6                                                                                                                     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 18:41 |
| L11 | 2        | "20040195701" and "34"                                                                                                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 18:41 |
| L12 | 2        | "20040195701" and "32"                                                                                                      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 18:41 |
| L13 | 199446   | (cte thermal expansion coefficient (co<br>adj efficient)) with (filling underfill\$4<br>fillet filiant fill\$4 epoxy resin) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:10 |
| L14 | 10219128 | "14" not 4                                                                                                                  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:10 |
| L15 | 793      | 13 not 4                                                                                                                    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:10 |
| L16 | 199446   | (cte thermal expansion coefficient (co<br>adj efficient)) with (filling underfill\$4<br>fillet filiant fill\$4 epoxy resin) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:10 |

## EAST Search History

|     |    |          |                                                                   |    |    |                  |
|-----|----|----------|-------------------------------------------------------------------|----|----|------------------|
| L17 | 80 | 16 not 8 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:10 |
| L18 | 72 | 3 and 17 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2007/07/01 20:11 |